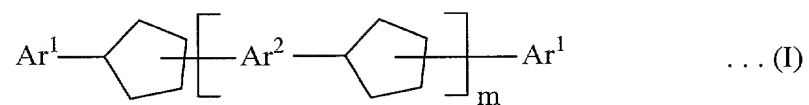
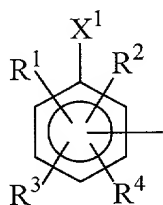
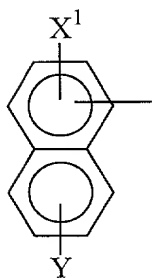


WHAT IS CLAIMED IS:

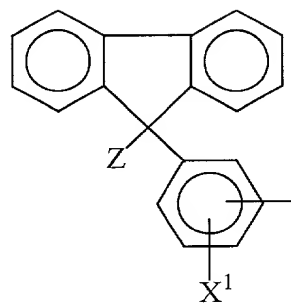
1. A compound represented by the following general formula (I):



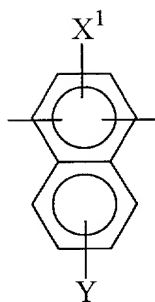
wherein m represents 0 or a positive number; Ar¹ represents at least one of monovalent organic groups represented respectively by



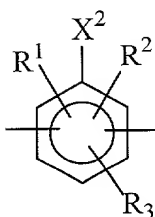
or



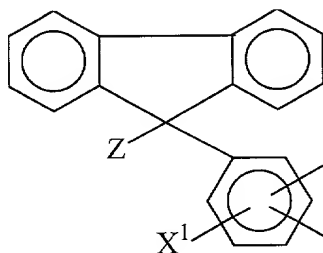
Ar² represents at least one of divalent organic groups selected from the group consisting of a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by



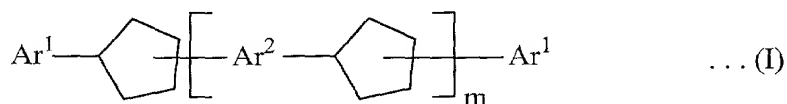
X^1 represents a 2,3-epoxypropoxyl group; X^2 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or

a 2,3-epoxypropoxyphenyl group; and R¹ to R⁴ are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom; and

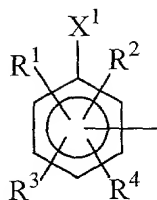
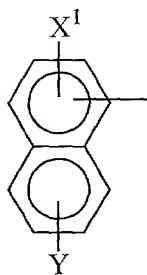
wherein, when m represents 0, Ar¹ groups are present in the 1 and 3 positions of the cyclopentane ring.

2. The compound according to claim 1, wherein the m is not more than 20 on the number average.

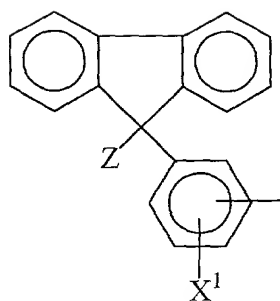
3. A compound which is a compound represented by the following general formula (I):



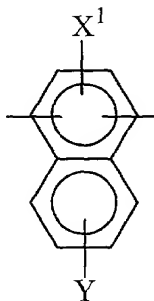
wherein m represents 0 or a positive number; Ar¹ represents at least one of monovalent organic groups represented respectively by



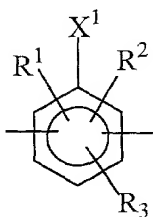
or



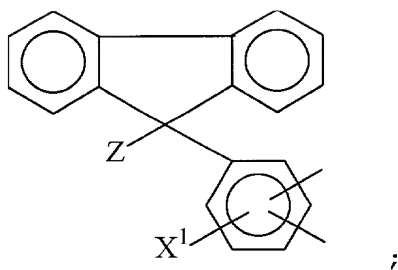
; Ar² represents at least one of divalent organic groups selected from the group consisting of a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by



X^1 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group; and R^1 to R^4 are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom;

and is a cooligomer containing as the groups Ar^2 the first atomic group and the second atomic group in one molecule;

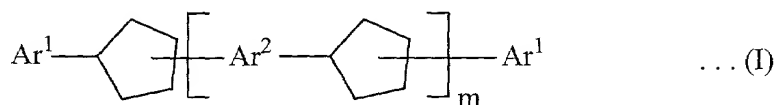
the number of said first atomic group and the number of said second atomic group being in a ratio of from 20:1 to 1:20; and

wherein, when m represents 0, Ar^1 groups are present in the 1 and 3 positions of the cyclopentane ring.

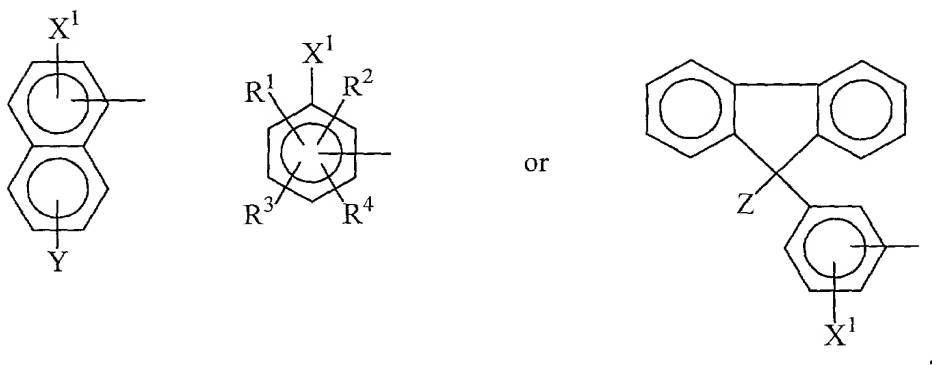
4. The compound according to claim 3, which further contains as the group Ar^2 the third atomic group in one molecule;

the total number of said first atomic group and second atomic group and the number of said third atomic group being in a ratio of from 9:1 to 8:2.

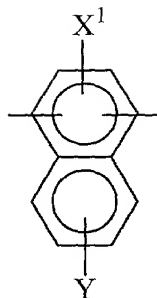
5. A compound represented by the following general formula (I):



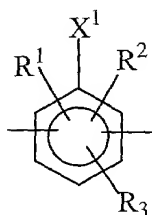
wherein m represents 0 or a positive number; Ar^1 represents at least one of monovalent organic groups represented respectively by



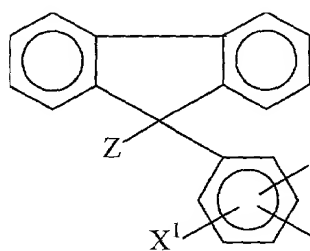
Ar^2 represents at least one of divalent organic groups selected from the group selected from a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by



;

X^1 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group;

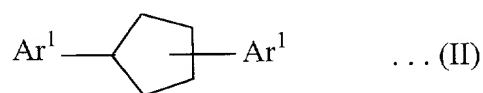
and R^1 to R^4 are each a group selected independently from the group selected from a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom;

and contains as the groups Ar^2 the third atomic group and either the first atomic group or the second atomic group and in one molecule;

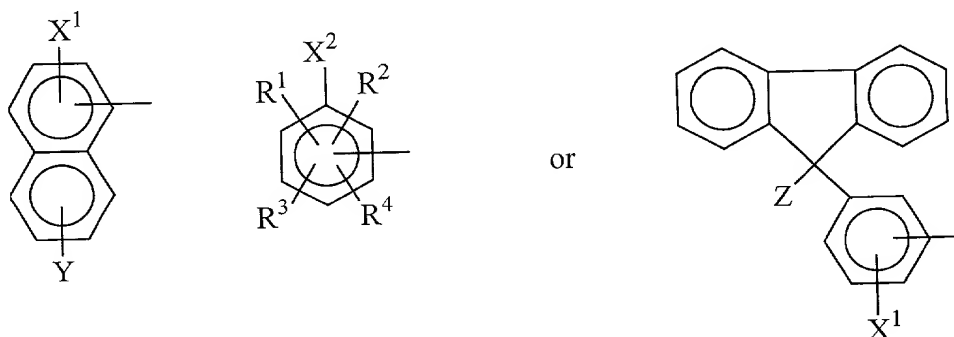
the number of said first atomic group or second atomic group and the number of said third atomic group being in a ratio of from 9:1 to 8:2; and

wherein, when m represents 0, Ar^1 groups are present in the 1 and 3 positions of the cyclopentane ring.

6. A compound represented by the following general formula (II):

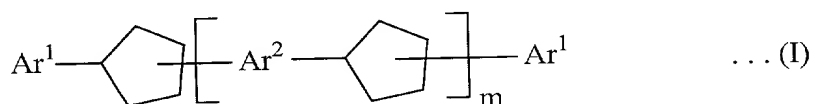


wherein Ar^1 represents at least one of monovalent organic groups represented respectively by

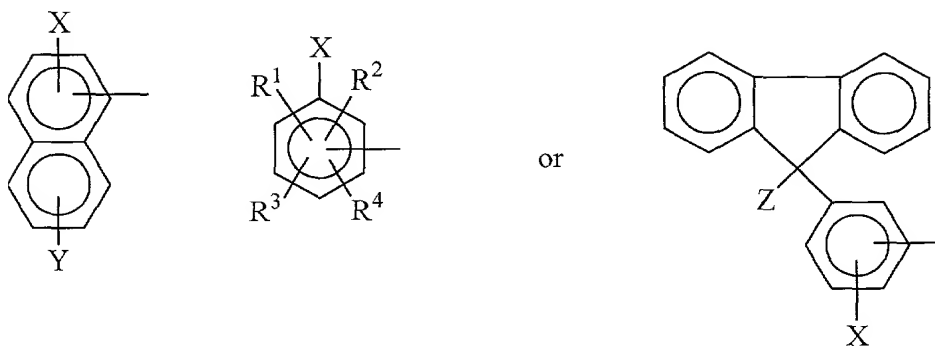


X^1 represents a hydroxyl group or a 2,3-epoxypropoxyl group; X^2 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group; and R^1 to R^4 are each a group selected independently from a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom.

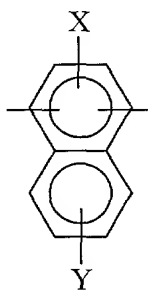
7. An epoxy resin composition comprising:
 an epoxy resin curing agent; and
 an epoxy resin containing at least one of a compound represented by the following general formula (I):



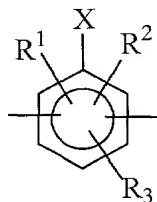
wherein m represents 0 or a positive number; Ar1 represents at least one monovalent organic groups represented respectively by



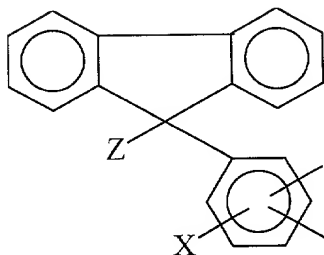
Ar2 represents at least one of divalent organic groups selected from a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by



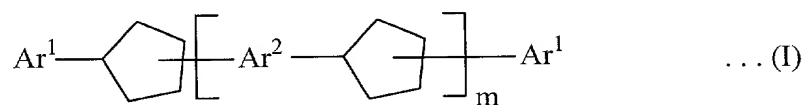
X represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group; at least one of X, Y and Z is a 2,3-epoxypropoxyl group; and R^1 to R^4 are each a group selected independently from a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom.

8. The epoxy resin composition according to claim 7, wherein said epoxy resin curing agent is contained in an equivalent of from 0.5 to 2.0 based on the number of epoxy groups of said epoxy resin.

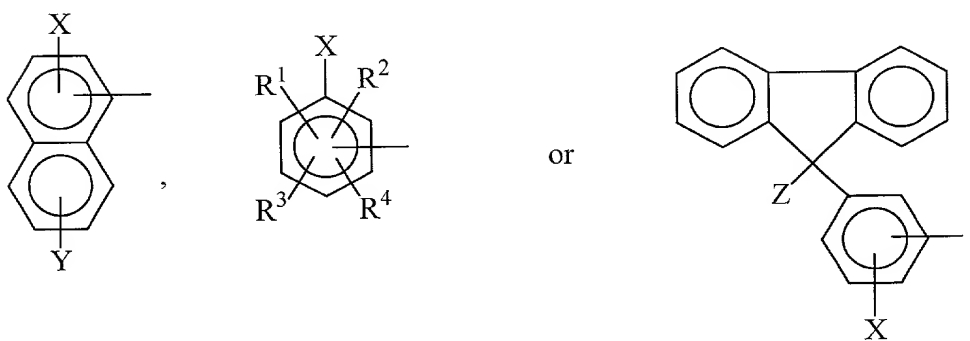
9. The epoxy resin composition according to claim 7, which further comprises an inorganic filler, wherein:

said inorganic filler being contained in an amount of 70 parts by weight or more of the total weight of the composition.

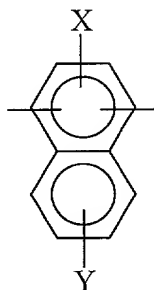
10. An epoxy resin molding material for encapsulating electronic devices which comprises at least one of a compound represented by the following general formula (I):



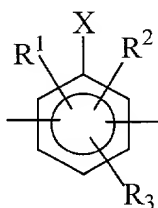
wherein m represents 0 or a positive number; Ar¹ represents at least one of monovalent organic groups represented respectively by



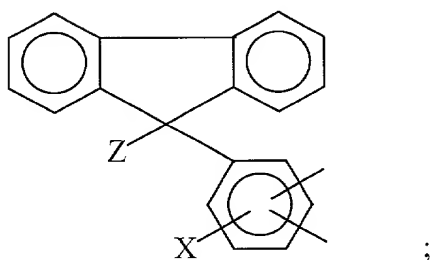
Ar² represents at least one of divalent organic groups selected from the group consisting of a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by



X represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group;

and R¹ to R⁴ are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom; and

wherein, when m represents 0, Ar¹ groups are present in the 1 and 3 positions of the cyclopentane ring.

11. The epoxy resin molding material for encapsulating electronic devices according to claim 10, wherein:

said compound is an epoxy resin in which at least one of X, Y and Z is a 2,3-epoxypropoxyphenyl group; and

which molding material further comprises an epoxy resin curing agent and an inorganic filler.

12. The epoxy resin molding material for encapsulating electronic devices according to claim 11, wherein:

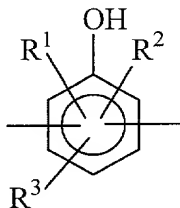
said epoxy resin curing agent is contained in an equivalent weight of from 0.7 to 1.3 based on the number of epoxy groups of said epoxy resin; and

said inorganic filler is contained in an amount of 70 parts by weight or more of the total weight of the molding material.

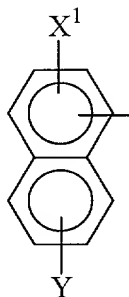
13. A resin-encapsulated electronic device comprising a device element and an encapsulating member which seals the device element, wherein:

said encapsulating member comprising a cured product of the epoxy resin molding material for encapsulating electronic devices according to claim 10.

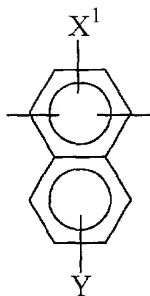
14. The compound according to claim 1, which further comprises, as a part of the Ar^2 groups contained in one molecule, a fourth atomic group represented by



15. The compound according to claim 1, wherein the Ar^1 is a monovalent organic group represented by

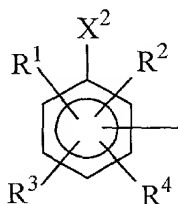


and the Ar^2 is a divalent organic group represented by

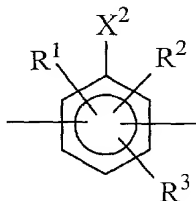


wherein X^1 represents a 2,3-epoxypropoxyl group; and Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group.

16. The compound according to claim 1, wherein the Ar^1 is a monovalent organic group represented by



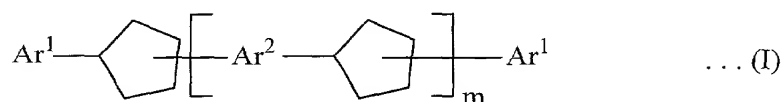
and the Ar^2 is a divalent organic group represented by



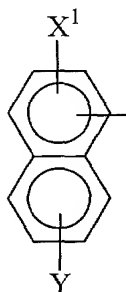
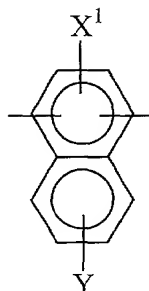
wherein X^2 represents a 2,3-epoxypropoxyl group; R^1 to R^4 are each a group selected independently from the group

consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom.

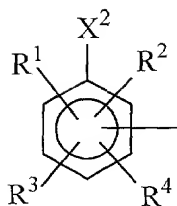
17. A compound which is a cooligomer represented by the following general formula (I):



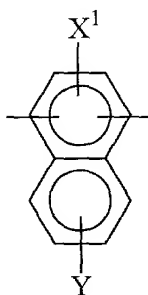
wherein m represents a positive number; Ar¹ represents at least one of monovalent organic groups selected from a fourth atomic group represented by



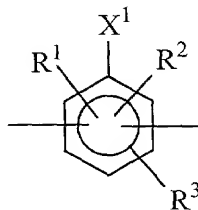
and a fifth atomic group represented by



Ar² represents at least one of divalent organic groups selected from a first atomic group represented by



and a second atomic group represented by



X¹ represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; and R¹ to R⁴ are each a group selected independently from a hydrogen atom, an alkyl group and an

aryl group having 1 to 10 carbon atoms and a halogen atom;

and contains in one molecule at least one of the first atomic group and the fourth atomic group and at least one of the second atomic group and the fifth atomic group.

18. The compound according to claim 17, wherein the total number of said first atomic group and said fourth atomic group and the total number of said second atomic group and said fifth atomic group are in a ratio of from 20:1 to 1:20.

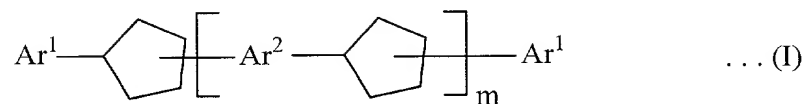
19. The compound according to claim 15, wherein the m is not more than 20 on the number average.

20. The compound according to claim 16, wherein the m is not more than 20 on the number average.

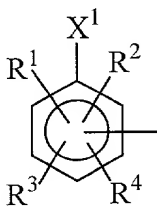
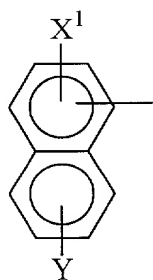
21. The compound according to claim 17, wherein the m is not more than 20 on the number average.

22. The compound according to claim 18, wherein the m is not more than 20 on the number average.

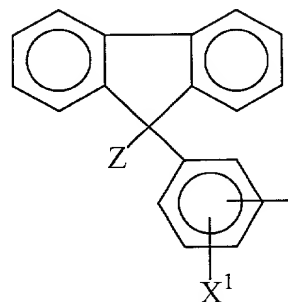
23. A compound represented by the following general formula (I):



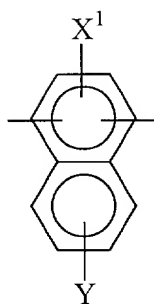
wherein m represents 0; Ar^1 represents at least one of monovalent organic groups represented respectively by



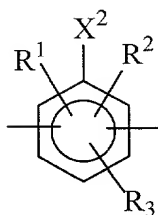
or



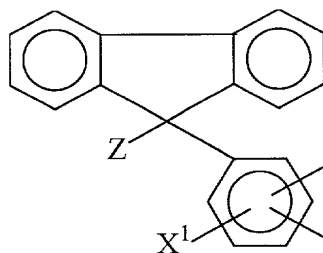
; Ar^2 represents at least one of divalent organic groups selected from the group consisting of a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by

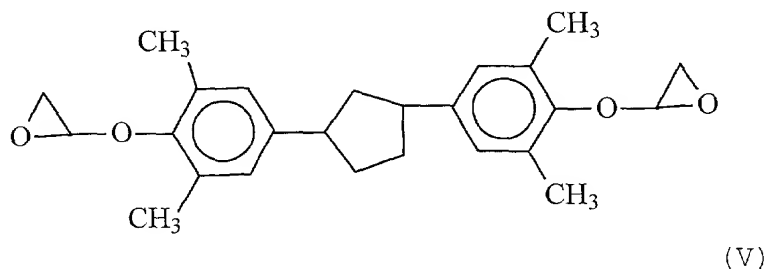


X^1 represents a 2,3-epoxypropoxyl group; X^2 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a

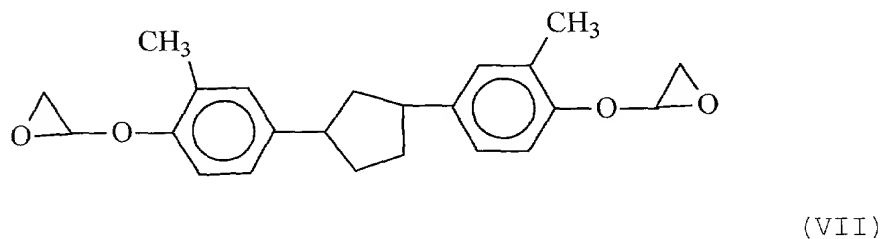
hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group;
and R¹ to R⁴ are each a group selected independently from
the group consisting of a hydrogen atom, an alkyl group
and an aryl group having 1 to 10 carbon atoms and a
halogen atom;

wherein, in formula (I), the Ar¹ groups are present
in the 1 and 3 positions of the cyclopentane ring.

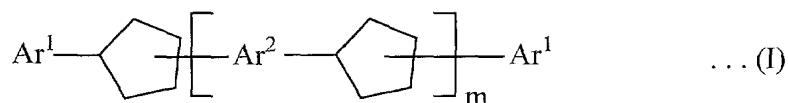
24. A compound according to claim 23 having the
formula (V)



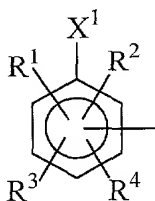
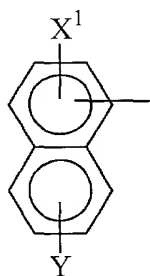
25. A compound according to claim 23 having the
formula (VII)



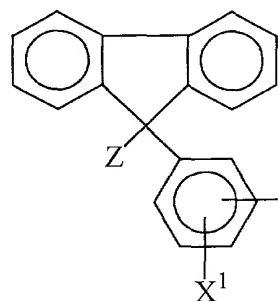
26. An epoxy resin molding material for encapsulating electronic devices which comprises at least one of a compound represented by the following general formula (I):



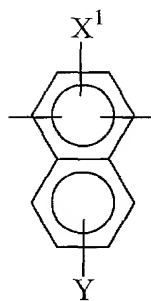
wherein m represents 0; Ar^1 represents at least one of monovalent organic groups represented respectively by



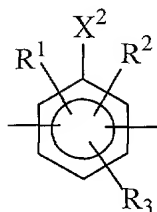
or



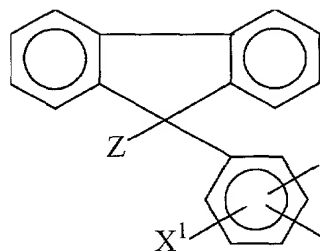
; Ar^2 represents at least one of divalent organic groups selected from the group consisting of a first atomic group represented by



a second atomic group represented by



and a third atomic group represented by

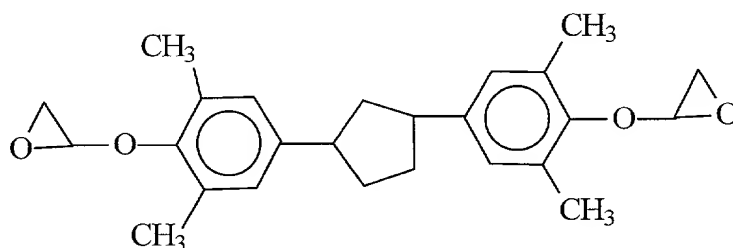


X^1 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group;

and R¹ to R⁴ are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom;

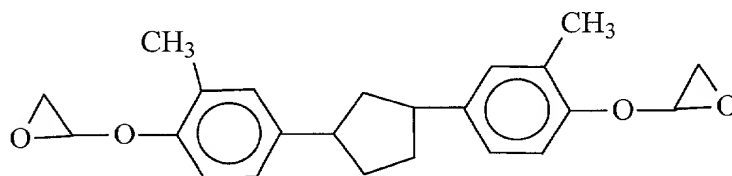
wherein, in formula (I), the Ar¹ groups are present in the 1 and 3 positions of the cyclopentane ring.

27. An epoxy resin molding material according to claim 26 including a compound represented by formula (V)



(V)

28. An epoxy resin molding material according to claim 26 including a compound having the formula (VII)



(VII)